

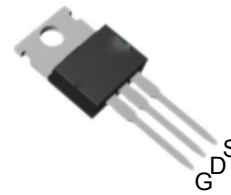
Features

- 40V/195A(package limited)/350A(silicon limited)
 $R_{DS(ON)}=1.4m\Omega(\text{typ.})@V_{GS}=10V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available
(RoHS Compliant)

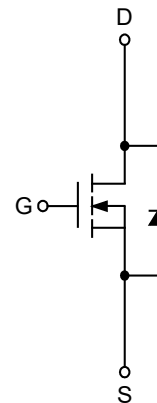
Applications

- SMPS Synchronous Rectification.
- BLDC Motor drive applications.
- Load Switch.
- DC-DC Conversion.
- Or-ing.

Pin Description



Top View of TO-220



N-Channel MOSFET

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V_{DSS}	Drain-Source Voltage		40	V
V_{GSS}	Gate-Source Voltage		± 20	
T_J	Maximum Junction Temperature		175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to 175	
I_S	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	195	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	195	
	Continuous Drain Current	$T_C=100^\circ\text{C}$	117	
I_{DM}^b	Pulsed Drain Current	$T_C=25^\circ\text{C}$	585	
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	136	W
		$T_C=100^\circ\text{C}$	68	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	0.4	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	Steady State	62.5	$^\circ\text{C}/\text{W}$
I_{AS}^c	Avalanche Current, Single pulse	$L=0.1\text{mH}$	72	A
E_{AS}^c	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	259	mJ

Note a : Maximum continuous current is limited by bonding wire.

Note b : Pulse width limited by maximum junction temperature.

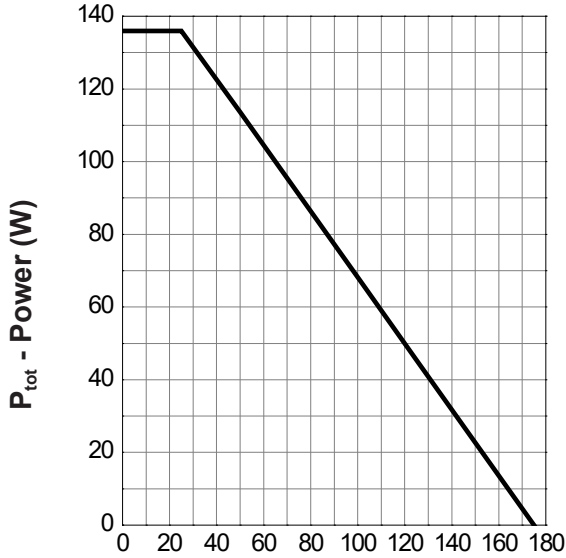
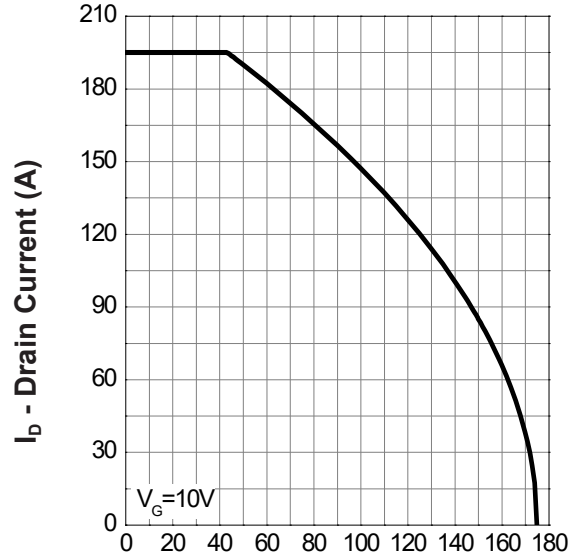
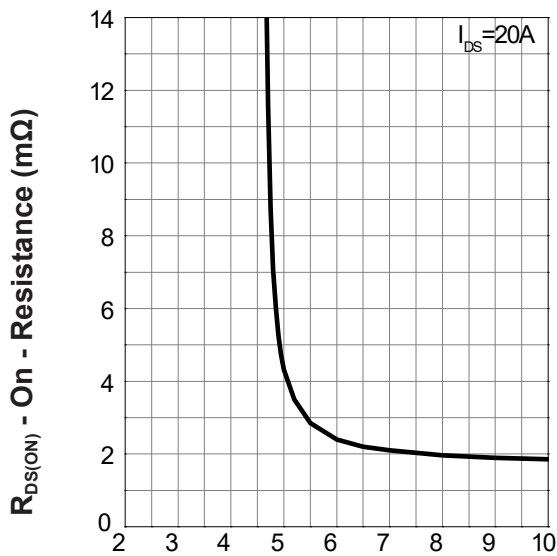
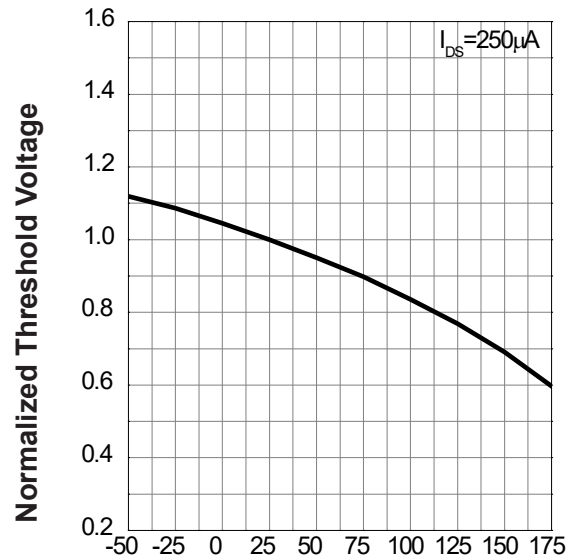
Note c : UIS tested and pulse width limited by maximum junction temperature (initial temperature $T_J=25^\circ\text{C}$).

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$ $T_J=85^\circ\text{C}$	-	-	1	μA
			-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	2	3	4	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
$R_{DS(ON)}^d$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=20A$	-	1.4	1.7	$m\Omega$
Gfs	Forward Transconductance	$V_{DS}=5V, I_{DS}=15A$	-	41.5	-	S
Diode Characteristics						
V_{SD}^d	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$	-	0.8	1.1	V
t_{rr}	Reverse Recovery Time	$I_{SD}=20A, di_{SD}/dt=100A/\mu s$	-	44.2	-	ns
t_a	Charge Time		-	22.6	-	
t_b	Discharge Time		-	21.6	-	
Q_{rr}	Reverse Recovery Charge		-	42.7	-	
Dynamic Characteristics ^e						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	2	4	Ω
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=20V,$ Frequency=1.0MHz	-	10347	-	pF
C_{oss}	Output Capacitance		-	1155	-	
C_{rss}	Reverse Transfer Capacitance		-	1058	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=20V, R_L=20\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	58.4	-	ns
t_r	Turn-on Rise Time		-	820	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	90.9	-	
t_f	Turn-off Fall Time		-	347.6	-	
Gate Charge Characteristics ^e						
Q_g	Total Gate Charge	$V_{DS}=20V, V_{GS}=10V,$ $I_{DS}=20A$	-	106	-	nC
Q_{gth}	Threshold Gate Charge		-	53.3	-	
Q_{gs}	Gate-Source Charge		-	28.4	-	
Q_{gd}	Gate-Drain Charge		-	49	-	

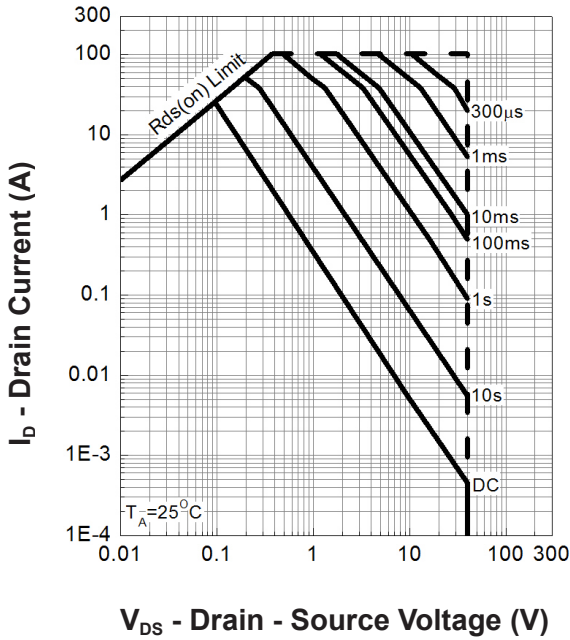
Note d : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Note e : Guaranteed by design, not subject to production testing.

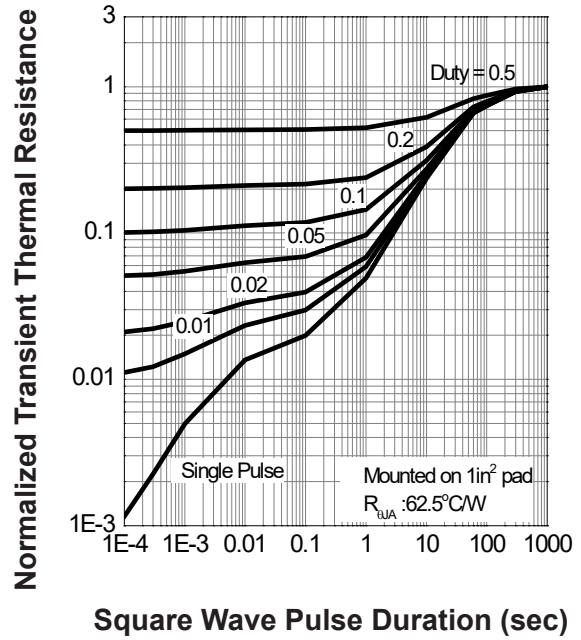
Typical Operating Characteristics
Power Dissipation

 T_c - Case Temperature (°C)
Drain Current

 T_c - Case Temperature (°C)
Gate-Source On Resistance

 V_{GS} - Gate - Source Voltage (V)
Gate Threshold Voltage

 T_j - Junction Temperature (°C)

Typical Operating Characteristics(Cont.)

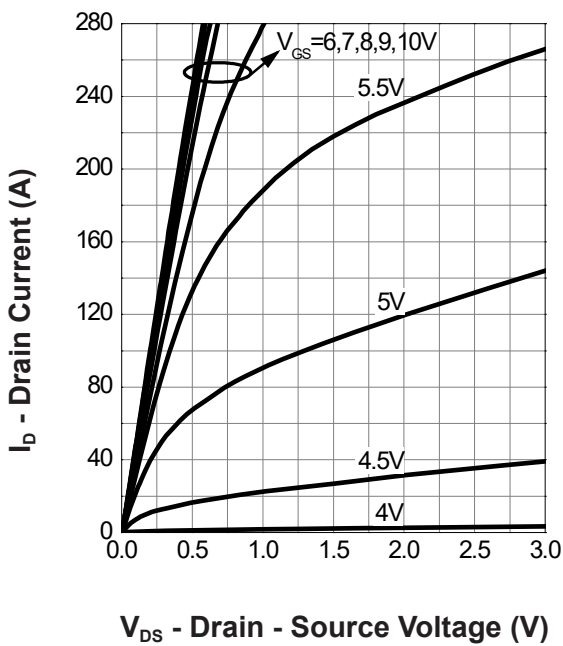
Safe Operation Area



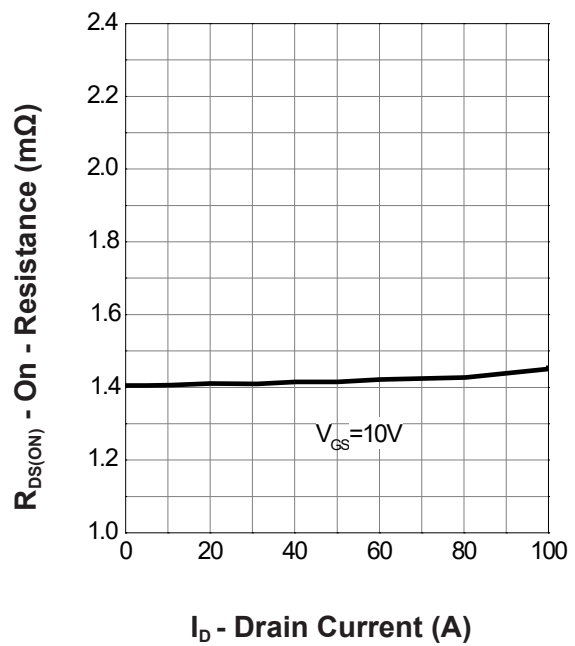
Thermal Transient Impedance

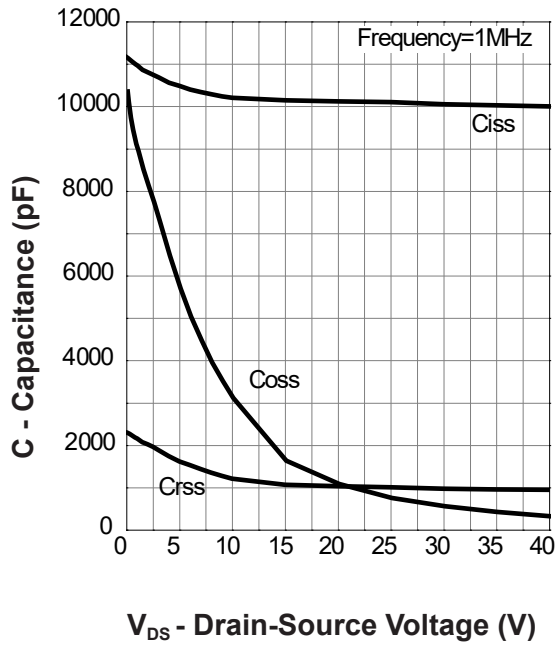
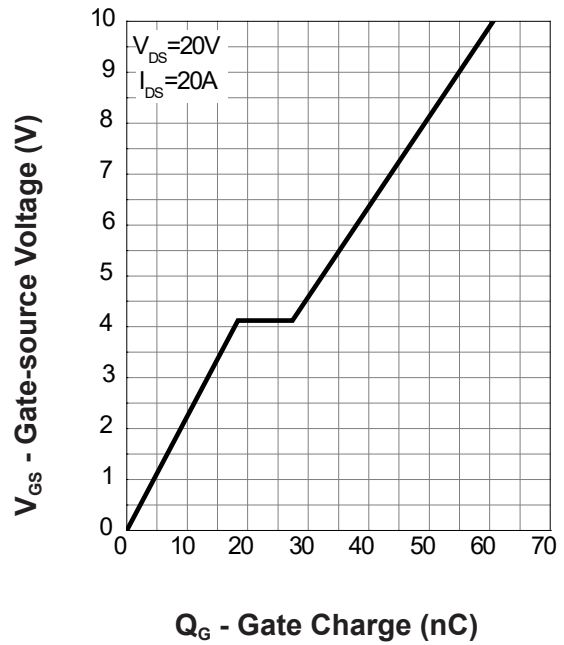
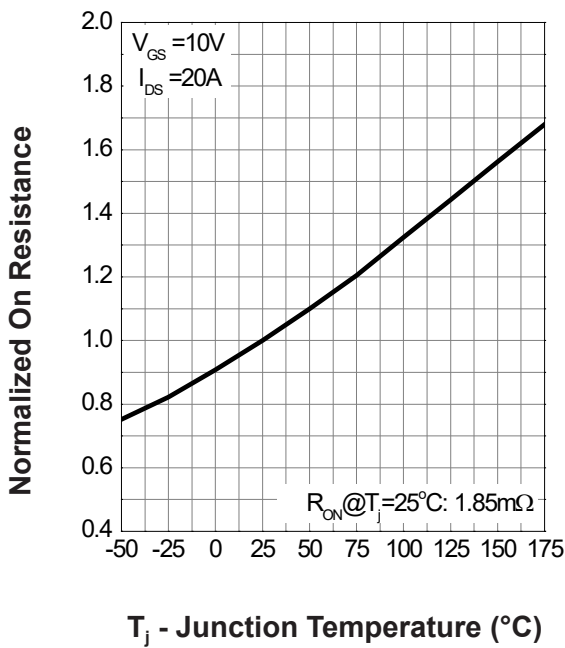
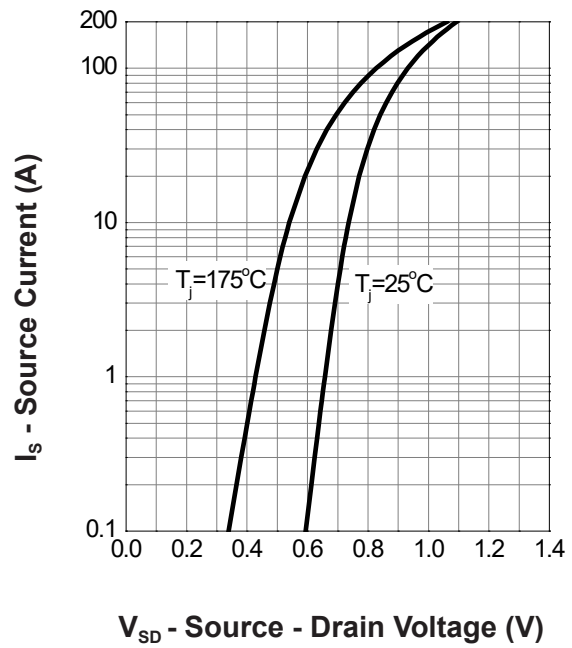


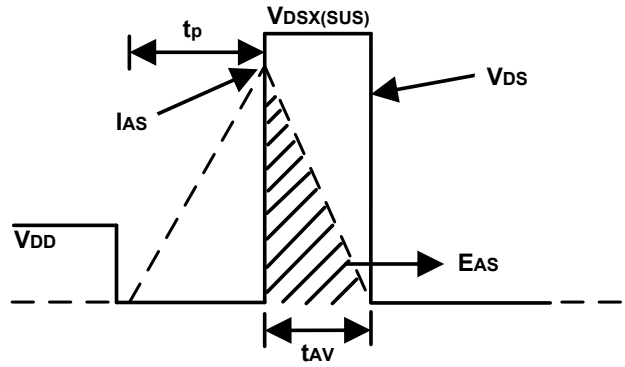
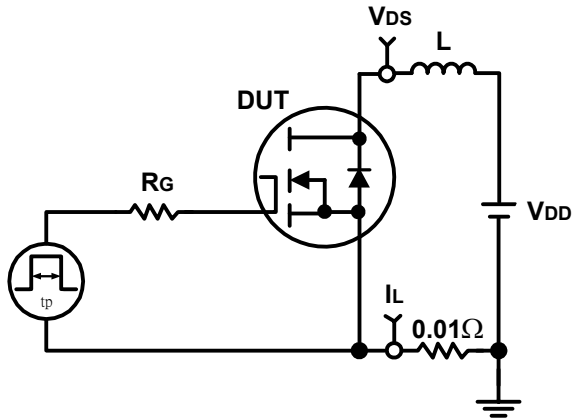
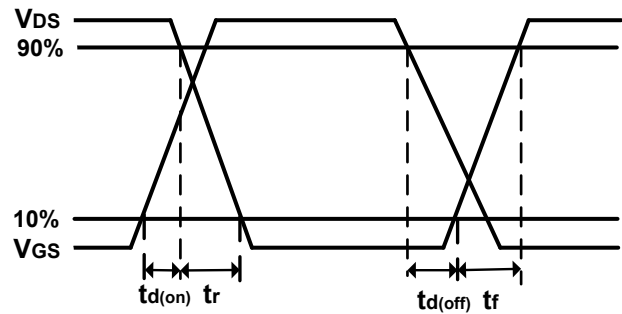
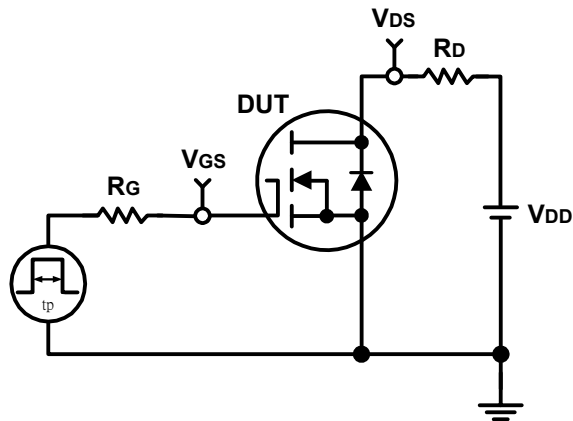
Output Characteristics



Drain-Source On Resistance

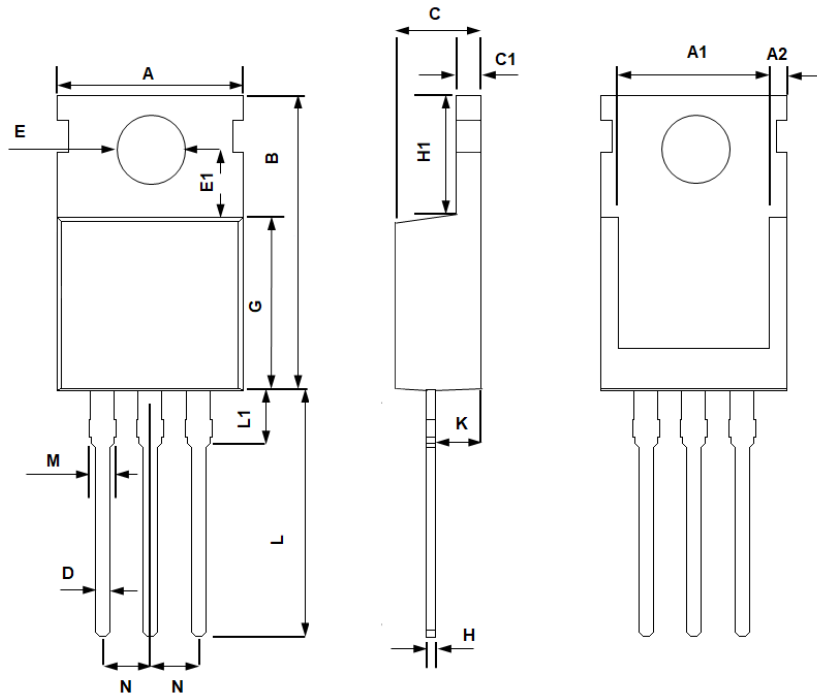


Typical Operating Characteristics(Cont.)
Capacitance

Gate Charge

Drain-Source On Resistance

Source-Drain Diode Forward


Avalanche Test Circuit and Waveforms

Switching Time Test Circuit and Waveforms


Package Information

TO-220



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.400	9.700	0.409	0.382
A1	8.900	7.400	0.350	0.291
A2	1.400	0.800	0.055	0.031
B	16.500	14.500	0.650	0.571
C	4.750	4.200	0.187	0.165
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	4.000	3.300	0.157	0.130
E1	3.800	3.400	0.150	0.134
G	9.400	8.400	0.370	0.331
H	0.600	0.200	0.024	0.008
H1	6.850	6.200	0.270	0.244
K	2.850	2.100	0.112	0.083
L	14.000	12.500	0.551	0.492
L1	4.000	2.700	0.157	0.106
M	1.750	1.100	0.069	0.043
N	2.640	2.440	0.104	0.096